

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT8180296

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SANTHOSH REDDY AKAVARAM	07/24/2023
	PRAKHAR SRIVASTAVA	07/10/2023
	SRIDHAR ANUMALA	07/18/2023
	RAMACHARAN SUNDARARAMAN	07/10/2023
	SONALI JABREVA	07/09/2023
	KHUSHBOO KUMARI	07/27/2023
	SANJAY VERDU	07/24/2023
RECEIVING PARTY DATA		
Name:	QUALCOMM INCORPORATED	
Street Address:	5775 MOREHOUSE DRIVE	
City:	SAN DIEGO	
State/Country:	CALIFORNIA	
Postal Code:	92121-1714	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	18338653	
CORRESPONDENCE DATA		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	202-776-7800	
Email:	QC.USPTO.inbox@duanemorris.com	
Correspondent Name:	DUANE MORRIS LLP - QC	
Address Line 1:	505 9TH ST. NW	
Address Line 2:	SUITE 1000	
Address Line 4:	WASHINGTON, D.C. 20004	
ATTORNEY DOCKET NUMBER:	G5452-00070	
NAME OF SUBMITTER:	JOAQUIN HERNANDEZ	
SIGNATURE:	/Joaquin Hernandez/	
DATE SIGNED:	09/21/2023	

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Total Attachments: 9

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ASSIGNMENT

WHEREAS, WE,

1. **Santhosh Reddy AKAVARAM**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
2. **Prakhar SRIVASTAVA**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
3. **Sridhar ANUMALA**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
4. **Ramacharan SUNDARARAMAN**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
5. **Sonali JABREVA**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
6. **Khushboo KUMARI**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
7. **Sanjay VERDU**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **APPARATUS AND METHODS FOR REDUCING LATENCIES ASSOCIATED WITH LINK STATE TRANSITIONS WITHIN DIE INTERCONNECT ARCHITECTURES** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to **U.S. Application No(s). 18/338,653** filed **June 21, 2023**, **Qualcomm Reference Number 2301754**, and all provisional applications relating thereto (and do hereby authorize **ASSIGNEE** and its representative to hereafter add herein such application number(s) and /or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

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AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States or in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to me respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Hyderabad, India on 07/24/2023
City, State, Country Date

Santhosh Reddy Akavaram
Santhosh Reddy AKAVARAM

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AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at	<u>Lucknow, Uttar Pradesh, India</u>	on	<u>07/10/2023</u>	<u><i>Prakhar</i></u>
	City, State, Country		Date	Prakhar SRIVASTAVA

Qualcomm Reference Number: 2301754

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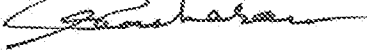
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AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Hyderabad, Telangana, India on 07/18/2023
City, State, Country Date


Sridhar Anumala
Sridhar ANUMALA

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at	San Jose, CA, United States	on	07/10/2023	
	City, State, Country		Date	Ramacharan SUNDARARAMAN

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Firozabad, India on 07/09/2023
City, State, Country Date

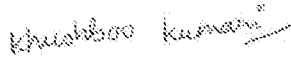


Sonali JABREVA

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AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at	Hyderabad, Telangana, India	on	07/27/2023	
	City, State, Country		Date	Khushboo KUMARI

Qualcomm Reference Number: 2301754
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AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Tirupati, Andhra Pradesh, India
City, State, Country

on 07/24/2023
Date


Sanjay VERDU